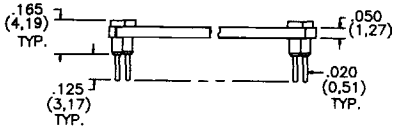


LOW PROFILE

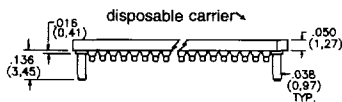


Specify Contact/Shell

- 001B** 30μ" Gold/200μ" Tin
- 002B** 30μ" Gold/10μ" Gold
- 011B** 10μ" Gold/200μ" Tin
- 014B** 200μ" Tin/200μ" Tin

PTH = .026 ± .003

FLUSH PROFILE PPC™



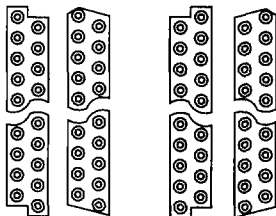
Specify Contact/Shell

- 710C** 30μ" Gold/200μ" Tin
- 711C** 30μ" Gold/10μ" Gold
- 714C** 200μ" Tin-Lead/200μ" Tin-Lead

PTH = .044 ± .003

PATTERN OPTIONS

Top View

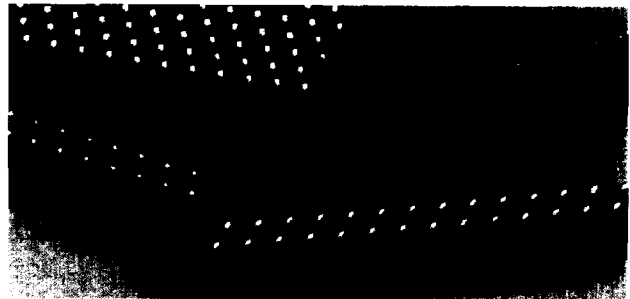


Standard Pattern Inverted Patterns

Insulators are
UL 94V-0 Rated
Thermoplastic

Features

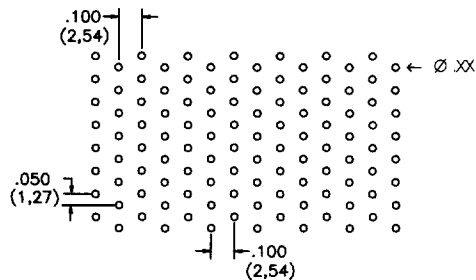
- For high density memory using vertical zig-zag in-line patterns
- Available in 16, 18, 20, 24, and 28 positions
- End-to-end and side-to-side stackability
- PPC™ option provides as low as .016" (0,41) above board profile — near flush
- Wide variety of contact styles available
- Use inverted style to create Quad in-line patterns — no insulator crossbars



Caption

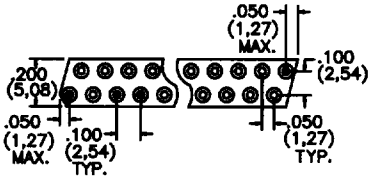
Ganged ZIP Pattern

- Ganged packages maximize device density
- Ganged ZIPs are available in arrays up to 20 ganged ZIPs of 32 pins each for a total of 640 pins
- Available in molded insulator or disposable PPC™



TYPICAL GANGED ZIP PCB LAYOUT

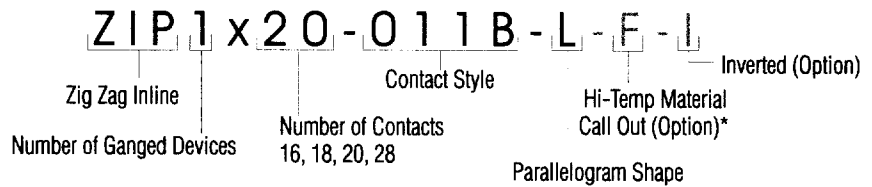
Parallelogram Insulators



VIEWED FROM TOP
OF CONTACTS



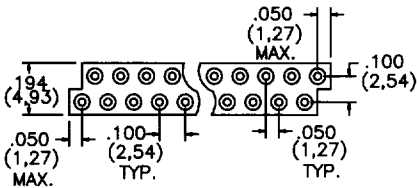
How To Order



*See page B1 for Material Callouts

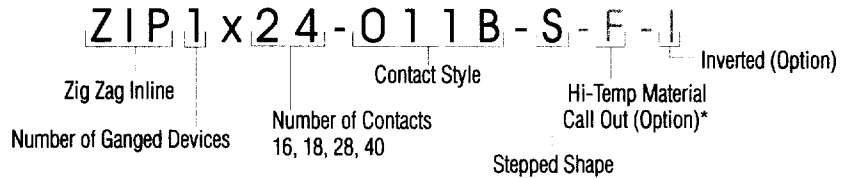


Stepped Insulators



VIEWED FROM TOP
OF CONTACTS

How To Order



*See page B1 for Material Callouts

Disposable Plastic Pin Carriers

- Available in a wide variety of contacts
- Ideal for flush profile or high-density ganged applications



Patent No. 4,420,877

How To Order

